

Product Description

The PE42440 is a HaRP[™]-enhanced SP4T RF switch developed on the UltraCMOS[®] process technology. This general-purpose switch contains 4 identical RF ports and can be used in a multitude of applications up to 3000 MHz. It integrates on-board CMOS control logic with a low voltage CMOScompatible control interface and requires no DC blocking capacitors. This RoHS-compliant part is available in a standard 3 x 3 x 0.75 mm QFN package.

Peregrine's HaRP[™] technology enhancements deliver high linearity and exceptional harmonics performance. It is an innovative feature of the UltraCMOS[®] process, providing performance superior to GaAs with the economy and integration of conventional CMOS.

Product Specification PE42440

SP4T UltraCMOS[®] RF Switch 50 – 3000 MHz

Features

- HaRP[™] Enhanced Technology for Unparalleled Linearity
- Very Low Insertion Loss: 0.45 dB @ 1000 MHz, 0.5 dB @ 2000 MHz
- Very High Isolation: 34 dB @ 1000 MHz, 28 dB @ 2000 MHz
- Exceptionally High ESD tolerance:
 - Class 3 (4.0 kV HBM) on RFC pin
 - Class 2 (2.0 kV HBM) on all pins
- Integrated Decoder for 2-pin control
 - Accepts 1.8V and 2.75V Control Logic Levels
- Low 4.5Ω Series ON Resistance
- No Blocking Capacitors Required



Figure 1. Functional Diagram

Figure 2. Package Type 16L 3 x 3 x 0.75 mm QFN



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Table 1. Electrical Specifications: Temp = 25 °C, V_{DD} = 2.75V ($Z_S = Z_L = 50\Omega$)

Parameter	Condition	Min	Тур	Max	Units
Operational Frequency		50		3000	MHz
	50 - 1000 MHz	-	0.45	0.65	dB
Insertion Loss (RFC - RFX)	1000 - 2000 MHz	-	0.5	0.7	dB
	2000 - 3000 MHz	-	0.85	1.15	dB
	50 - 1000 MHz	-	22	-	dB
Return Loss (RFC - RFX, Active Ports)	1000 - 2000 MHz	-	15	-	dB
	2000 - 3000 MHz	-	11	-	dB
	50 - 1000 MHz	31	34	-	dB
Isolation (RFC - RFX)	1000 - 2000 MHz	25	28	-	dB
	2000 - 3000 MHz	20	22	-	dB
Input IP2 50 - 3000 MHz, +18 dBm per tone, 1 MHz spacing			96		dBm
Input IP3 50 - 3000 MHz, +18 dBm per tone, 1 MHz spacing			67		dBm
P1dB ¹ 50 - 3000 MHz			41.5		dBm
Switching time 50% CNTL to 10/90% of RF			2		μs

Note: 1. Please refer to Maximum Operating Pin (50 Ω) in Table 4

Table 2. Electrical Specifications, Worst Case Conditions: Temp = 85 °C, V_{DD} = 2.65V ($Z_S = Z_L = 50\Omega$)

Parameter	Condition	Min	Тур	Max	Units
Operational Frequency		50		3000	MHz
	50 - 1000 MHz	-	0.5	0.65	dB
Insertion Loss (RFC - RFX)	1000 - 2000 MHz	-	0.65	0.75	dB
	2000 - 3000 MHz	-	1.0	1.25	dB
	50 - 1000 MHz	-	21	-	dB
Return Loss (RFC - RFX, Active Ports)	1000 - 2000 MHz	-	15	-	dB
	2000 - 3000 MHz	-	10	-	dB
	50 - 1000 MHz	30	32	-	dB
Isolation (RFC - RFX)	1000 - 2000 MHz	24	26	-	dB
	2000 - 3000 MHz	20	22	-	dB
Input IP2 50 - 3000 MHz, +18 dBm per tone, 1 MHz spacing			95		dBm
Input IP3 50 - 3000 MHz, +18 dBm per tone, 1 MHz spacing			66		dBm
P1dB ¹ 50 - 3000 MHz			41		dBm
Switching time	50% CNTL to 10/90% of RF		2		μs

Note: 1. Please refer to Maximum Operating Pin (50 Ω) in Table 4



Figure 3. Pin Configuration (Top View)



Table 3. Pin Descriptions

Pin No.	Pin Name	Description	
1	GND	Ground	
2	V _{DD}	Supply	
3	V2	Switch control input, CMOS logic level	
4	V1	Switch control input, CMOS logic level	
5	GND	Ground	
6	RF4 ¹	RF Port 4	
7	GND	Ground	
8	RF3 ¹	RF Port 3	
9	GND	Ground	
10	GND	Ground	
11	RFC ¹	RF Common	
12	GND	Ground	
13	RF1 ¹	RF Port 1	
14	GND	Ground	
15	RF2 ¹	RF Port 2	
16	N/C	No Connect	
Paddle	GND	Exposed ground paddle	

Notes: 1. All RF pins must be DC blocked with an external series capacitor or held at 0 V_{DC}

Table 4. Operating Ranges⁴

Parameter	Symbol	Min	Тур	Мах	Units
V _{DD} Supply Voltage	V _{DD}	2.65	2.75	3.3	V
I_{DD} Power Supply Current $(V_{DD} = 2.75V)$	I _{DD}		13	50	μΑ
RF input power (50Ω) (50 - 500 MHz) (500 - 3000 MHz)	P _{IN}			+28 +33	dBm dBm
Control Voltage High	VIH	1.4			V
Control Voltage Low	VIL			0.4	V
Temperature Range	T _{OP}	-40	+25	+85	°C
Storage Temperature Range	T _{ST}	-65	+25	+160	℃

Note: 1. Operation should be restricted to the limits in the Operating Ranges table

Table 5. Absolute Maximum Ratings

Symbol	Parameter/Conditions	Min	Max	Units
V _{DD}	Power supply voltage	-0.3	4.0	V
Vi	Voltage on any DC input		V _{DD} + 0.3	V
P _{IN} (50Ω) ¹	RF input power (50 - 500 MHz) (500 - 3000 MHz)		+28 +33	dBm dBm
	HBM ² ESD Voltage, RFC pin		4000	V
V _{ESD}	HBM ² ESD Voltage, all pins		2000	V
	MM ESD Voltage, RFC pin		300	V
	MM ESD Voltage, all pins		100	V

Notes: 1. V_{DD} within operating range specified in *Table 4* 2. ESD Voltage (HBM, MIL-STD-883 Method 3015.7)

Exceeding absolute maximum ratings may cause permanent damage. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

Table 6. Truth Table

Path	V2	V1
RFC – RF1	0	0
RFC – RF2	1	0
RFC – RF3	0	1
RFC – RF4	1	1

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS[®] device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the specified rating.

Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS[®] devices are immune to latch-up.

Moisture Sensitivity Level

The Moisture Sensitivity Level rating for the PE42440 in the 16-lead 3 x 3 x 0.75 mm QFN package is MSL1.

Switching Frequency

The PE42440 has a maximum 25 kHz switching rate.

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Evaluation Kit

The SP4T switch EK Board was designed to ease customer evaluation of Peregrine's PE42440. The RF common port is connected through a 50 Ω transmission line via the top SMA connector, J1. RF1, RF2, RF3 and RF4 are connected through 50 Ω transmission lines via SMA connectors J3, J5, J2 and J4, respectively. A through 50 Ω transmission is available via SMA connectors J6 and J7. This transmission line can be used to estimate the loss of the PCB over the environmental conditions being evaluated.

The board is constructed of a four metal layer FR4 material with a total thickness of 62 mils. The middle layers provide ground for the transmission lines. The transmission lines were designed using a coplanar waveguide with ground plane model using a trace width of 32 mils, trace gaps of 25 mils, and metal thickness of 2.1 mils.

Figure 5. Evaluation Board Schematic

Peregrine Specification 102-0339-02

Figure 4. Evaluation Board Layouts

Peregrine Specification 101-0287-03





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Typical Performance Data

Figure 6. Insertion Loss: RFC-RF @ 25 °C



Figure 8. Isolation: RFC-RF @ 25 ℃



Figure 7. Insertion Loss: RFC-RF @ 2.75V



Figure 9. Isolation: RFC-RF @ 2.75V







Figure 10. Return Loss at Active Port @ 25 °C

Figure 11. Return Loss at Active Port @ 2.75 V

Figure 12. Maximum Operating Power vs. Frequency





Figure 13. Package Drawing

16-lead 3 x 3 x 0.75 mm QFN



Figure 14. Marking Specifications

SIDE VIEW



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